## **Orthodyne 3600Plus** Large Wire Bonder

## **Versatility Plus**

Combining innovation and experience with the proven 3600 platform, Orthodyne has introduced, not only the fastest, most productive large wire bonder, but also the first wire bonder configurable to PowerRibbon<sup>™</sup> on the market – the new 3600Plus. The 3600Plus establishes the latest in motion control technology, software, testing, and monitoring capabilities for power modules, automotive packages and other MCM applications.

To bring you unprecedented process monitoring, Orthodyne linked non-destructive pulltesting technology (ALC) and the optional Bond Process Monitoring (BPM) system, now available for frontand rear cut.

The 3600Plus features the latest digital ultrasonic generator technology and the largest variety of bondhead configurations for large wire to handle virtually any package type.

With the newest Orthodyne GSIII PR system or the optional Cognex PatMax<sup>®</sup>, the 3600Plus provides the most versatile pattern recognition system available. The large 300mm x 300mm work table or the Offline Programming Tool (OPT) offer additional options.

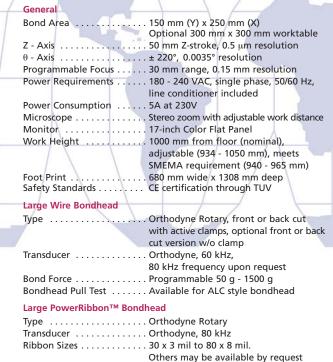
The pluses built into the 3600Plus are made possible through Orthodyne's experience and understanding of changing customer needs. With a commitment to outstanding performance, exceptional customer service and ongoing product development, we've made a better bonder even better.

B

**ORTHODYNE** <sup>®</sup>

**ELECTRONICS** 

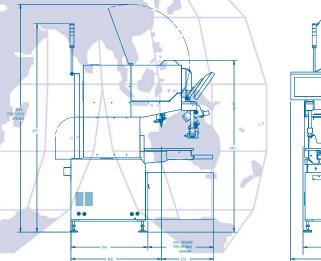
# Specifications



#### Wire Handling Large Wire

Wire Range
Wire Feed Motorized wire dereeler with optical encoder
Missing Wire Detection Wire deformation monitoring
Max. Wire Looping 40.0 mm
Minimum Wire Length
Detection
Wire Spool Size
10 - 11 mm ID
Pattern Recognition/Optics
Vision System Enhanced Orthodyne GSIII Pattern

	Recognition System
Digital Zoom Available	5 ,
Die Rotation	$\pm$ 7 degrees from nominal for point and dual point mode, $\pm$ 20 degrees from nominal for edge mode
System Configuration	
CPU	VME PowerPC, for RTS (Real Time Server)
	CPCI Pentium, for DM (Data Manager)
File Storage	Hard disk, CDRW
Comm. Ports	Serial port, Ethernet, USB,
	SECS/GEM interface (optional)
Discrete I/O Lines	Standard: 32 lines. Expanded I/O (up to 64 lines) optional. Two 32- line
	ports available on front panel
Operating System	VxWorks for Real Time Function
	Windows XP for Graphical User Interface
Number of Bonds/Program	5000 bonds
	Digital Zoom Available   Die Rotation   System Configuration   CPU   File Storage   Comm. Ports   Discrete I/O Lines



# Made the **Orthodyne Way**

The new 3600Plus represents a new wire bonder platform that meets today's advanced packaging challenges. Its technology delivers high productivity, process stability, low cost of ownership (COO) and the flexibility to grow with market demands.

The design of this new product family is based on decades of experience. Since 1962 Orthodyne has developed and perfected its core competencies in Motion Technology, Pattern Recognition and Ultrasonics.

Offering complete solutions with award-winning support, investing long-term to excel in an ever-changing industry and pairing leading-edge technology with customer dedication is the Orthodyne way.



16700 Redhill Ave., Irvine CA 92606 phone 949-660-0440 / fax 949-660-0444 www.orthodyne.com sales@orthodyne.com

> An ISO 9001 and ISO 14001 Company

All rights reserved. Copyright 2006. Orthodyne Electronics Corporation. Specifications subject to change without notice

Bulletin 36-305

Authorized Orthodyne Representative:

# **3600Plus** Large Wire Bonder PowerRibbon<sup>™</sup> Bonder





# **Unprecedented Productivity**

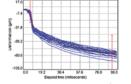
# uncompromised quality

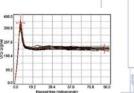
#### **Active Loop** Control **Bondheads** (ALC)

Available as Front or Rear Cut version, the bondhead design provides excellent loop control and non-destructive pulltest capability

### **Bond Process** Monitoring **Optional** system

monitors bond deformation and ultrasonic signal in real-time. Suspect bonds are flagged and vital process information can be stored for evaluation.





Area

(Y) x 50mm (Z) pro-

and deep packages

and space for con-

venient manual or

automatic loading

of parts. A 300 mm

large table option is

(X) x 300mm (Y)

& ORTHODYNE

REF. TOP PLATE

Enhanced PR

Enhanced third gen-

eration system (GSIII)

repeatability through

a variety of powerful

every device. Optional

offers accuracy and

tools for virtually

Cognex PR System

including PatMax<sup>®</sup>

available.

available.

vides access for large

## **Multiple Bond** Frequencies

THE

Multiple bond frequency options are available. All bond frequencies are supported through OE proprietary digital generator technology.

# expandable cutting edge capabilities

Networking Simple Networking via Ethernet. SECS/GEM is available as an option.

## File Handling

CDRW, hard drive, USB and networking provide easy-to-use tools for data transfer. data storage, and program back-up.

## **Open Machine** Large Work Desian & System

Architecture Completely open table design allows open access from below the work area. Complicated shuttle and clamping systems as well as line integration are simple and inexpensive. The table can be completely removed or replaced

to make room for any customized clamping scheme

# cost of ownership

## Speed

Low-mass bondhead and unique XY table desian combined with high performance linear motors and advanced motion control technology result in the most productive large wire bonders on the market.

## **New Low-**Maintenance

Bondhead Low maintenance bondhead features a modular design that is easy to set-up and maintain resulting in higher uptime.

#### **Deep Access** Capabilities 250mm (X) x 150mm

All Orthodyne bondheads are re-designed for improved clearance around the bond tool for deep access packages.

## Alternative Bondhead Configurations

3600Plus is available with front and back cut bondheads. This flexibility guarantees the best bondhead configuration for your specific package.

## **On-Board** Diagnostics Continuous feedback

B: 2: 3.00 .

of major equipment functions results in higher uptime and controlled performance.



**3600Plus** Large Wire Bonder PowerRibbon<sup>™</sup> Bonder

## "Per Bond" Parameters

3600Plus Software makes virtually every bond parameter programmable on a "per bond" level. This customization assures maximum flexibility and bond quality for even the most advanced packages.

## **Programmable** Force Control

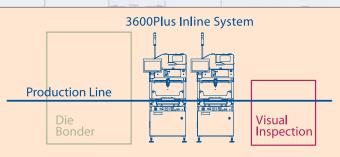
The 3600Plus bondhead features Orthodyne's thirdgeneration programmable forcer. The improved accuracy and linearity throughout the bond force range ensures a consistent bond process.

### Advanced Looping Algorithms Constant loop

length or height are just two of many looping features available.







#### WORKHOLDER PLATFORM

#### Software

New GUI-based software structure offers simplified and user-friendly machine operation and sophisticated trouble shooting tools resulting in lower training cost and increased uptime

## Manual To Fully Automatic

The standard 3600Plus can be loaded manually, for use in a prototype lab or low volume production. At the same time, automation and integration of the system is simple and inexpensive.

## **Available Options**

**Bond Process Monitoring Option (BPM)** detects process variations real-time. Process feedback can be stored locally or shared with a host system.

Back Cut Bondhead provides added clearance and allows cutting on a sensitive surface (i.e., die).

**Extra Deep Access Bondhead Kits** accommodate deeper package designs.

**Programmable Status Light Tower** features three programmable lights as well as an audio alarm feature.

**Removable Casters** facilitate the relocation of the 3600Plus.

Large Moving Work Table expands the work area to 300 mm x 300 mm.



Offline Programming Tool (OPT) lets you convert existing CAD files into machine process programs, significantly increasing machine uptime.

Bondhead Lighting Options offer solutions for every possible application.

**SECS/GEM Protocols** are supported for various factory automation systems.

**PowerRibbon™ Option** converts your large wire system into a PowerRibbon bonder, capable of processing Al Ribbon in sizes 30 x 3 mil to 80 x 8 mil.

## Cognex PR System including PatMax®

